The Silicon Vertex Detector of the Belle II Experiment

Yuma Uematsu (UTokyo) on behalf of the Belle II SVD group

uematsu@hep.phys.s.u-tokyo.ac.jp

Outline

Introduction

Operation & Performance

Beam background & Radiation effect

Conclusions

Introduction

Belle II/SuperKEKB



Belle II Vertex Detector

Requirements

Better vertex resolution than Belle to compensate reduced Lorentz boost

• improved point resolution, reduced inner radius and lower material

Operate in high background environment

expected hit rate: 3 MHz/cm² @ SVD layer-3

Radiation hard

expected 0.2 Mrad/yr. @ SVD layer-3

Layers-1-2: Pixel Detector (PXD) → talk by Boqun Wang

DEPFET pixel sensors

Innermost layer 1.4 cm from interaction point

Layers-3-6: Silicon Vertex Detector

Diamond sensors
For radiation monitor and beam abort



Strip sensors

(SVD)

Pixel sensors

(PXD)

Beam pipe

Belle II Silicon Vertex Detector (SVD)

Layer-3-6: Silicon Vertex Detector (SVD)
 Double-sided Si strip detectors (DSSDs)
 Low material budget: 0.7% X₀ per layer

SVD Roles

- Extrapolate tracks to PXD
 - essential for reconstruction of decay verticesPXD region of interest for data reduction
- Stand-alone tracking for low p_T tracks
- Precise vertexing of K_s
- PID with d*E*/dx

DSSDs

- Provide 2-D spatial information
- Strips are AC-coupled to n-type substrate
- Fully depleted at 20-60 V, operated at 100 V
- Total: 172 sensors = 1.2 m² sensor area = 224k readout strips









readout Al

Belle II Silicon Vertex Detector (SVD)

Layer-3-6: Silicon Vertex Detector (SVD)
 Double-sided Si strip detectors (DSSDs)
 Low material budget: 0.7% X₀ per layer

SVD Roles

- Extrapolate tracks to PXD
 - essential for reconstruction of decay vertices
 - PXD region of interest for data reduction
- Stand-alone tracking for low p_T tracks
- Precise vertexing of K_s
- PID with d*E*/dx

DSSDs

- Provide 2-D spatial information
- Strips are AC-coupled to n-type substrate
- Fully depleted at 20-60 V, operated at 100 V
- Total: 172 sensors = 1.2 m² sensor area = 224k readout strips



172 sensors	125 40	125 60	126 [mm] 61 ←→41
	x14 Small	x120	x38 Trapezoidal
# of p-strips*	768	768	768
p-strip pitch*	50 µm	75 µm	50-75 µm
# of n-strips*	768	512	512
n-strip pitch*	160 µm	240 µm	240 µm
thickness	320 µm	320 µm	300 µm
manufacturer	HPK		Micron

*readout strips - one floating strip on both sides

Front-end ASIC: APV25

- Originally developed for CMS silicon tracker
- Fast: 50 ns shaping times
- Radiation hard: > 100 Mrad
- Power consumption: 0.4 W/chip (700 W in total)
- 128 channel inputs per chip
- Operated in "multi-peak" mode @ ~32 MHz
 - Bunch-crossing frequency ~8*32 MHz, clock not synchronous with them as in CMS
 - 6 subsequent samples read-out
- 3/6-mixed acquisition mode prepared for higher luminosity
 To reduce background occupancy, trigger dead-time and data-size
 Half time-window, half FIFO usage and half data-size for each hit in 3-sample
 - Switching sampling number according to the timing precision of trigger trigger arrival
 - The functionality already implemented in the real setup and confirmed to work
 - few hours of physics data-taking was smooth
 - Performance study needed before moving to 3/6-mixed mode
 - Hit efficiency is the first step \rightarrow slide 16
 - To be checked: position resolution, dE/dx, hit-time



Front-end ASIC: APV25

- Originally developed for CMS silicon tracker
- Fast: 50 ns shaping times
- Radiation hard: > 100 Mrad
- Power consumption: 0.4 W/chip (700 W in total)
- 128 channel inputs per chip
- Operated in "multi-peak" mode @ ~32 MHz
 - Bunch-crossing frequency ~8*32 MHz, clock not synchronous with them as in CMS
 - 6 subsequent samples read-out
- 3/6-mixed acquisition mode prepared for higher luminosity
 To reduce background occupancy, trigger dead-time and data-size
 Half time-window, half FIFO usage and half hit-by-hit data-size in 3-sample
 - Switching sampling number according to the timing precision of trigger trigger arrival
 - The functionality already implemented in the real setup and confirmed to work
 - few hours of physics data-taking was smooth
 - Performance study needed before moving to 3/6-mixed mode
 - Hit efficiency is the first step \rightarrow slide 16
 - To be checked: position resolution, dE/dx, hit-time



Origami chip on sensor concept

Readout chips directly on each middle sensor

- Shorter signal propagation length (smaller capacitance and noise)
- Thinned to 100 μm to reduce material budget
- Wrapped flex to read both sides from the same side

■ Cool only one side with bi-phase –20 °C CO₂





Yuma Uematsu

Operation & Performance

Operational experience

SVD installed in 2018, operated since 2019

Reliable and smooth operation without major problems
 Total fraction of masked strips ~ 1%

One APV25 chip disabled in spring 2019 (out of 1748)

 \rightarrow fixed by cable reconnection in summer 2019

Excellent detector performance

already shown at <u>Vertex 2020</u>

Hit efficiency stably > 99% in most of the sensors

Reasonable cluster charge distribution

u/P side: agrees with MIP considering uncertainty in calibration
 v/N side: 10-30% due to large pitch and floating strip

Very good SNR (most probable value: 13-30)

updated simulation better agrees with data

 \rightarrow YSF talk by Mateusz Kaleta



Cluster position resolution $\rightarrow YSF$ talk by Robin Leboucher

Preliminary cluster position resolution measured on e⁺e⁻ → μ⁺μ⁻ data
 Estimated from the residual of the cluster position with respect to the track (unbiased)
 Effect of the track extrapolation error subtracted

Excellent position resolution in agreement with the expectations from the pitch
 Still room for improvement for the u/P side (work ongoing)



Yuma Uematsu

Hit-time resolution

Excellent hit-time resolution with respect to event time
 Event time estimated by central drift chamber (CDC) outside of SVD
 (~ 2.9 ns u/P, ~ 2.4 ns v/N)

Possible to efficiently reject off-time background hits
 Will be used for higher luminosity and background levels



3-sample acquisition mode

Performance

Ideal 3 samples provide enough information as 6 samples

- amplitude peak ADC sample
- hit-time rising edge of the waveform
- Degrades if the trigger timing is largely shifted
 - CDC event time is a good estimator
- 1st step: relative hit efficiency
 (hit efficiency in 3-sample)/(~ in 6-sample)
 Emulate 3-sample mode offline
 Efficiency based on track using CDC, SVD and PXD
 - Relative efficiency > 99.9% for trigger timing shift within ±30 ns
 - almost a whole clock-cycle



3-sample acquisition mode

Performance

Ideal 3 samples provide enough information as 6 samples

- amplitude peak ADC sample
- hit-time rising edge of the waveform
- Degrades if the trigger timing is largely shifted
 - CDC event time is a good estimator
- 1st step: relative hit efficiency
 - (hit efficiency in 3-sample)/(~ in 6-sample)
 - Emulate 3-sample mode offline
 - Efficiency based on track using CDC, SVD and PXD
 - Relative efficiency > 99.9% for trigger timing shift within ±30 ns
 - almost a whole clock-cycle



16/24

Beam background & Radiation effect

Beam background and hit occupancy

Beam background increases SVD hit occupancy which degrades tracking performance

- Present occupancy limit in layer-3: ~ 3%
 - will be loosened to x~2 using hit-time to reject background
- With current luminosity, average hit occupancy in layer-3 is well under control (< 0.5%)
- Projection of hit occupancy at $L = 8 \times 10^{35} \text{ cm}^{-2} \text{s}^{-1}$ is about 3% in layer-3
 - estimated by scaling MC with data/MC ratio
 - correspond to dose of ~ 0.2 Mrad/smy
 - $^\circ~$ = 1-MeV neutron fluence of $\sim~5{\times}10^{11}~n_{eq}/cm^2/smy$
 - smy: Snowmass Year = 10⁷ sec
 - Long term BG extrapolation affected by large uncertainties
 - optimization of collimator settings in MC
 - injection BG not included in data nor MC
 - \rightarrow motivate VXD upgrade \rightarrow talk by Katsuro Nakamura



Yuma Uematsu

Integrated dose

 SVD dose estimated by dose on diamond sensors: 70 krad in layer-3 mid plane (the most exposed to radiation)

Dose estimate based on correlation between SVD occupancy and diamonds dose

Several assumptions and large uncertainty (~ 50%)

1-MeV equivalent neutron fluence:
 1.6×10¹¹ n_{eq}/cm² in first 2.5 years
 assuming dose/n_{eq} fluence ratio
 = 2.3×10⁹ n_{eq}/cm²/krad from MC



• physics trigger \rightarrow Poisson trigger w/o injection veto

remove over estimation



Int. dose in SVD - New coeff. (from exp. 12 & 16) + EODB correction (from 14/2102)

Radiation effect on leakage current

- Good linear correlation between leakage current and estimated dose
- Slope: 2-5 µA/cm²/Mrad with large variations due to temperature effects and dose spread among sensors in layer (average dose in layer used in estimate)
- Same order of magnitude as BaBar measurement (1 μA/cm²/Mrad @ 20 °C)
 - [NIMA 729, 615-701, 2013]
- Strip noise from leakage current is suppressed by short shaping time (50 ns) in APV25
 - comparable to the strip-capacitive noise only after 10 Mrad irradiation \rightarrow not problematic for 10 years (2 Mrad)



2021/9/27 - Vertex 2021

Yuma Uematsu

Radiation effect on strip noise

Noise increase of 20-25% in layer-3

Not affecting performance

Likely due to radiation effects on sensor surface

• Non-linear increase due to fixed oxide charges that increase inter-strip capacitance, expected to saturate

Saturation seen on v/N side and starting to be seen on u/P



Noise average [e-]

Radiation effect on depletion voltage

v/N side strip noise drops at full depletion
 v/N side insulated only when the n-type bulk is fully depleted
 Over-depletion bias still slightly decrease noise
 by reducing electron accumulation layer on v/N side surface



v/N side

No change in full depletion voltage observed with time
 Consistent with low integrated neutron fluence (~1.6 × 10¹¹ n_{eq}/cm²)

L3.5.1 v/N Side - Strip Noise



L3.5.1 N Side - Noise

2021/9/27 - Vertex 2021

Yuma U<u>ematsu</u>

Conclusions

 SVD has been taking data in Belle II since March 2019 smoothly and reliably

Excellent performance in agreement with expectations
 Still some room for improvement in cluster position resolution

 Observed first effects of radiation damage at the expected level but not affecting performance

Ready to cope with increased beam background
 Reject off-time background using hit-time

3/6-mixed acquisition mode to reduce dead time, data size and occupancy

Thank you!

YSF talks on Belle II SVD:

"Measurement of the cluster position resolution of the Belle II Silicon Vertex Detector" by Robin Leboucher

Simulation of the Belle II Silicon Vertex Detector" by Mateusz Kaleta

Backup

Signal charge and signal-to-noise ratio

Signal charge: normalized for the track path length in silicon
 u/P side: agree with MIP considering ~ 15% uncertainty in APV25 gain calibration
 v/N side: 10-30% signal loss due to large pitch and presence of floating strip
 similar in all sensors

SNR: very good in all sensors (most probable value: 13-30)
 u/P side: larger noise due to longer strip length (larger inter-strip capacitance)



2021/9/27 - Vertex 2021

Yuma Uematsu



Hit-time estimation

Neighboring strips over threshold are grouped into 'cluster' APV samples for strips a_{strip 0}, a_{strip 2}, a_{strip 2}, are summed up:





3-sample acquisition mode

efficiency

- emulate 3-sample mode offline using trigger timing information
- based on tracks using CDC, SVD and PXD hits
- > 99.4% for trigger jitter less than 30 ns

efficiency compared to 6-sample
 3-sample efficiency/6-sample efficiency
 > 99.9% for trigger jitter less than 30 ns
 almost a whole clock-cycle

